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Development Board EPC9088 Quick Start Guide

*High Frequency Class-E Wireless Power Amplifier,
Using EPC2115*

Revision 1.0



DESCRIPTION

The EPC9088 is a high efficiency, differential mode Class-E amplifier development board that can operate up to 10 MHz. The purpose of this development board is to simplify the evaluation process of class-E amplifier technology using eGaN® IC's by allowing engineers to easily mount all the critical class-E components on a single board that can be easily connected into an existing system.

This board may also be used for applications where a low side switch is utilized. Examples include, and are not limited to, push-pull converters, and current-mode Class-D amplifiers.

The amplifier board features the 150 V rated EPC2115 eGaN IC, which is an eGaN FET with integrated gate driver. The amplifier is set to operate in differential mode and can be re-configured to operate in single ended mode. The integrated gate driver allows a 5 V logic signal to drive the power FET. The EPC9088 board is provided with a logic supply regulator allowing the logic and gate driver to be powered from 7.5 V though 12 V.

For more information on the EPC2115 eGaN IC's please refer to the datasheet available from EPC at www.epc-co.com. The datasheet should be read in conjunction with this quick start guide.

DETAILED DESCRIPTION

The Amplifier Board

Figure 1 shows the schematic of a single ended class-E amplifier with ideal operation waveforms where the amplifier is connected to a tuned load such as a highly resonant wireless power coil. The amplifier has not been configured due to the specific design requirements such as load resistance and operating frequency. The design equations of the specific class-E amplifier support components are given in this guide and specific values suitable for a RF amplifier application can then be calculated.

Figure 2 shows the differential mode class-E amplifier EPC9088 demo board power circuit schematic. In this mode the output is connected between Out 1 and Out 2. A block-wave external oscillator with 50% duty cycle and 0 V – 5 V signal amplitude is used to control the board. Duty cycle modulation is recommended only for advanced users who are familiar with the class-E amplifier operation and required additional efficiency.

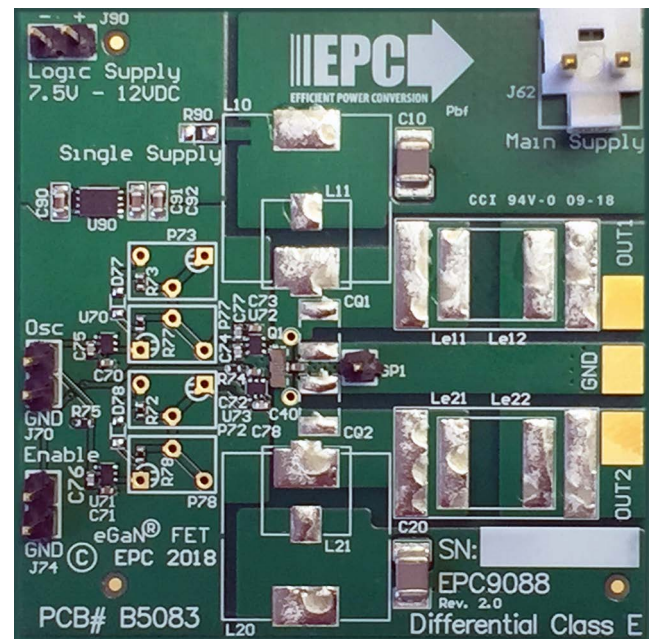
The EPC9088 is also provided with a 5 V regulator to supply power to the logic circuits and gate driver of the eGaN IC. Adding a zero ohm resistor in position R90 allows the EPC9088 to be powered using a single supply voltage; however in this configuration the operating voltage is limited to between 7 V and 12 V.

Operation of the class-E amplifier can be disabled by either driving or pulling the Enable input low which disables the oscillator signal from the input of both FETs. The default configuration of the board is Enabled internally using a 10 kΩ pull up resistor.

Table 1: Performance Summary ($T_A = 25^\circ\text{C}$) EPC9088

| Symbol | Parameter | Conditions | Min | Max | Units |
|-----------|-----------------------------------|------------------------------------|------|-----|-------|
| V_{IN} | Main Supply Voltage Range | Class-E Configuration | 0 | 30 | V |
| | | Current Mode Class-D Configuration | 0 | 26 | V |
| | | Push-Pull Configuration | 0 | 60 | V |
| V_{DD} | Gate Drive Input Supply Range | | 7 | 12 | V |
| I_{OUT} | Switch Node Output Current (each) | | | 2* | A |
| V_{OSC} | Oscillator input threshold | Input 'Low' | -0.3 | 1.5 | V |
| | | Input 'High' | 3.5 | 5 | V |
| V_{EN} | Enable input threshold | Input 'Low' | -0.3 | 1.5 | V |
| | | Input 'High' | 3.5 | 5 | V |

* Maximum current depends on die temperature – actual maximum current will be subject to switching frequency, bus voltage and thermal cooling.



EPC9088 board.

Single-ended Mode operation

Although the default configuration is differential mode, the demo board can be re-configured for single ended operation by connecting the load between Out 1 and GND only or Out 2 and GND only (see figure 2 and 5 for details). It is important to note that BOTH FETs will always be operational in differential mode therefore the output that is not used MUST be disabled by removing the corresponding choke inductor.

Class E amplifier operating limitations

The impact of load resistance variation is significant to the performance of the class-E amplifier, and must be carefully analyzed to select the optimal design resistance.

The impact of load resistance (R_{Load} – Real part of Z_{Load}) variation on the operation of the class E amplifier is shown in figure 3. When operating a class E amplifier with a load resistance (R_{Load} – Real part of Z_{Load}) that is below the design value (see the waveform on the left of figure 3), the load tends to draw current from the amplifier too quickly. To compensate for this condition, the amplifier supply voltage is increased to yield the required output power. The shorter duration of the energy charge cycle leads to a significant increase in the voltage to which the switching device is exposed. This is done in order to capture sufficient energy and results in device body diode conduction during the remainder of the device off period. This period is characterized by a linear increase in device losses as a function of decreasing load resistance (R_{Load}).

When operating the class-E amplifier with a load resistance (R_{Load}) that is above the design value (see the waveform on the right of figure 3), the load tends to draw insufficient current from the amplifier, resulting in an incomplete voltage transition. When the device switches, there is residual voltage across the device, which leads to shunt capacitance ($C_{OSS} + C_{sh}$) losses. This period in the cycle is characterized by an exponential increase in device losses as a function of increasing reflected load resistance.

Given these two extremes of the operating load resistance (R_{Load}), the optimal point between them must be determined. In this case, the optimal point yields the same device losses for each of the extreme load resistance points and is shown in the lower center graph of figure 3. This optimal design point can be found through trial and error, or by using circuit simulation.

Class-E amplifier design

For this amplifier only three components need to be specifically designed; 1) the extra inductor (L_e), 2) the shunt capacitor (C_{sh}), and 3) the selection of a suitable switching device. The RF choke (L_{RFck}) value is less critical and hence can be chosen or designed.

The design equations for the class E amplifier have been derived by N. Sokal [1]. To simplify these equations, the value of QL in [1] is set to infinity, which is a reasonable approximation in most applications within the frequency capability of this development board. The design needs to have a specific load resistance (R_{Load}) value and desired load power (P_{Load}) that is used to begin the design, which then drives the values of the other components, including the magnitude of the supply voltage.

The class-E amplifier passive component design starts with the load impedance value (Z_{Load}) shown in figure 1. The reactive component of Z_{Load} is tuned out using a series capacitor C_s , which also serves as a DC block, resulting in R_{Load} . It is a common mistake to ignore the need for the DC block, where a failure to do so can yield a DC current from the supply through to the load, and leads to additional losses in several components in that path.

First, using the equations in figure 4, both the extra inductor L_e (equation 2) and shunt capacitor (equation 3) values can be determined [2], [3]. The value of the shunt capacitor includes the C_{OSS} of the switching device, which must be subtracted from the calculated value to yield the actual external capacitor (C_{sh}) value. To do this, first the magnitude of the supply voltage (V_{DD}) is calculated using equation 1, which in turn can be used to determine the peak device voltage ($3.56 \cdot V_{DD}$).

The RMS value of the peak device voltage is then used to determine the C_{OSSQ} of the device at that voltage. This is the capacitance that will be deducted from the calculated shunt capacitor to reveal the external shunt capacitor (C_{sh}) value. The C_{OSSQ} of the device can be calculated by integrating the C_{OSS} as function of voltage using equation 4. If the C_{OSSQ} value is larger than the calculated shunt capacitance, then the design cannot be realized for the load resistance specified and a new load resistance (R_{Load}) must be chosen.

Finally, the choke (L_{RFck}) can be designed using equation 5 and, in this case, a minimum value is specified. Larger values yield lower ripple current, which can lead to a more stable operating amplifier. A too-low value will lead to increased operating losses and change the mode of operation of the amplifier. In some cases this can be intentional.

Here:

R_{Load} = Load Resistance [Ω]

P_{Load} = Load Power [W]

V_{DD} = Amplifier Supply Voltage [V]

f = Operating frequency [Hz]

L_e = Extra Inductor [H]

C_{sh} = Shunt Capacitor [F]

C_{OSS} = Output Capacitance of the FET [F]

C_{OSSQ} = Charge equivalent device output capacitance [F].

V_{DS} = Drain-Source Voltage of the FET [V]

L_{RFck} = RF Choke Inductor [H]

C_s = Series tuning capacitor [F]

Z_{Load} = Load Impedance [Ω]

Note. For differential mode amplifier design details, please refer to the application note 'AN021: eGaN FETs for Low Cost Resonant Wireless Power Applications'.

[1] N.O. Sokal, "Class-E RF Power Amplifiers," QEX, Issue 204, pp. 9–20, January/February 2001.

[2] M. Kazimierzczuk, "Collector amplitude modulation of the class E tuned power amplifier," IEEE Transactions on Circuits and Systems, June 1984, Vol.31, No. 6, pp. 543–549.

[3] Z. Xu, H. Lv, Y. Zhang, Y. Zhang, "Analysis and Design of Class E Power Amplifier employing SiC MESFETs," IEEE International Conference on Electron Devices and Solid-State Circuits (EDSSC) 2009, 25–27 December 2009, pp 28–31.

QUICK START PROCEDURE

The EPC9088 amplifier board is easy to set up to evaluate the performance of the eGaN IC in a class-E amplifier application. Once the design of the passive components has been completed and installed, then the board can be powered up and tested.

1. Make sure the entire system is fully assembled prior to making electrical connections including an applicable load.
2. With power **off**, connect the **main** input power supply bus to J62 as shown in figure 5. Note the polarity of the supply connector. Set the voltage to 0 V.
3. With power **off**, connect the logic input power supply bus to J90 as shown in figure 5. Note the polarity of the supply connector. Set the voltage to between 7 V and 12 V.
4. Make sure all instrumentation is connected to the system. This includes the external oscillator to control the circuit.
5. Turn on the logic supply voltage.

6. Turn on the main supply voltage and increase to the desired value. Note operating conditions and in particular the thermal performance and voltage of the FETs to prevent over-temperature and over-voltage failure.
7. Once operation has been confirmed, observe the device voltage, efficiency and other parameters on both the amplifier and device boards.
8. For shutdown, please follow steps in the reverse order.

NOTE. When measuring the high frequency content switch-node, care must be taken to avoid long ground leads. An oscilloscope probe connection (preferred method) has been built into the board to simplify the measurement of the Drain-Source Voltage (shown in figure 5). The choice of oscilloscope probe needs to consider tip capacitance where this will appear in parallel with the shunt capacitance thereby altering the operating point of the amplifier.

PRE-CAUTIONS

The EPC9088 development board showcases the EPC2112 eGaN IC's in a class-E amplifier application. Although the electrical performance surpasses that of traditional silicon devices, their relatively smaller size does require attention paid to thermal management techniques.

The EPC9088 development board has no current or thermal protection and care must be exercised not to over-current or over-temperature the

devices. Excessively wide load impedance range variations can lead to increased losses in the devices. The operator must observe the temperature of the gate driver and eGaN FETs to ensure that both are operating within the thermal limits as per the datasheets. Always check operating conditions and monitor the temperature of the EPC devices using an IR camera.

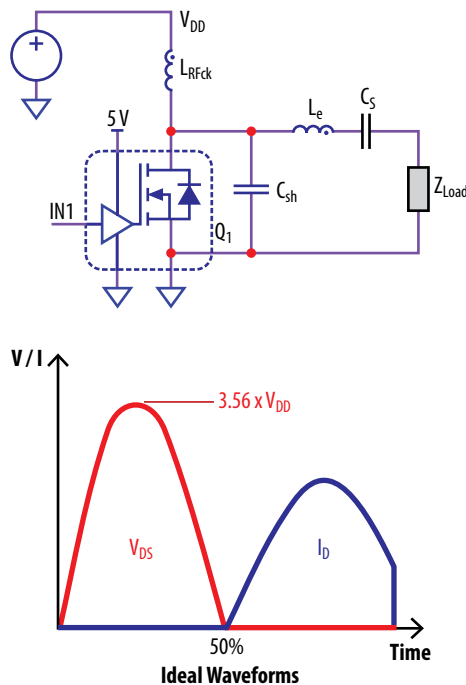


Figure 1: Single-ended Class-E Amplifier with ideal operation waveforms.

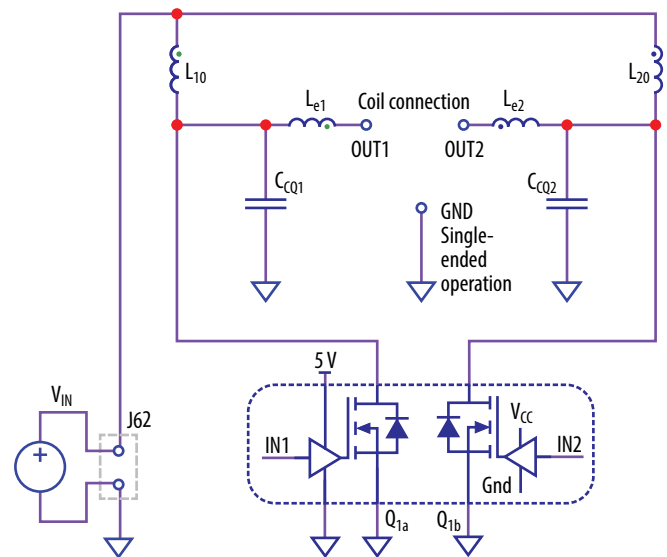


Figure 2: EPC9088 power circuit schematic.

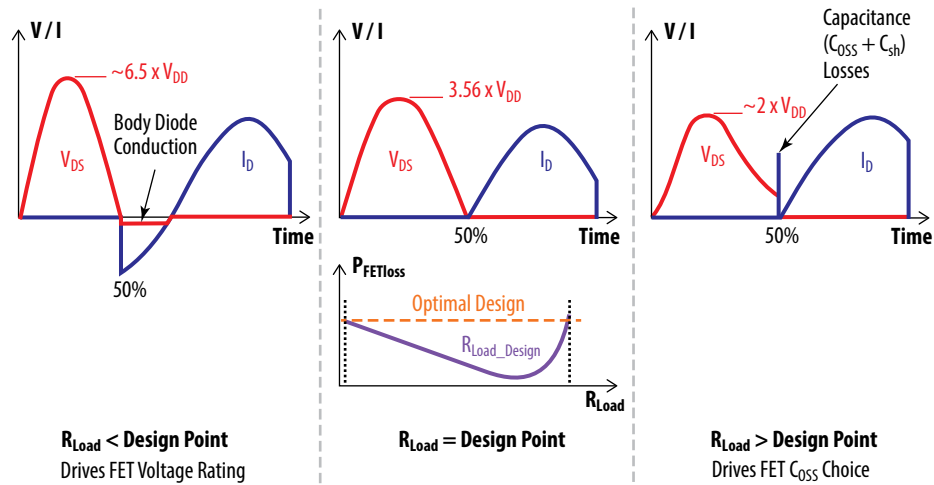


Figure 3: Class-E operation under various load conditions that can be used to determine the optimal design load resistance (R_{Load}).

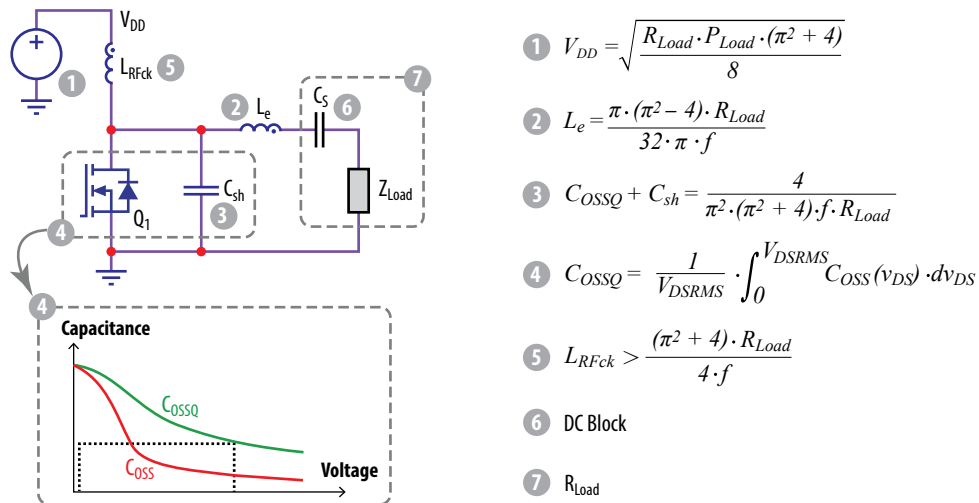


Figure 4: Class E amplifier design process with equations.

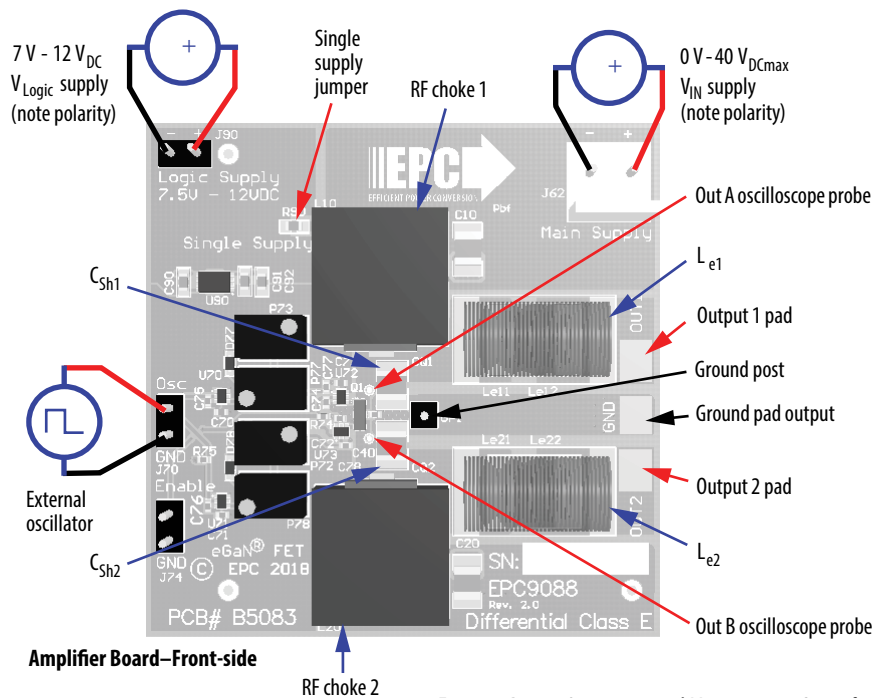


Figure 5: Proper Connection and Measurement Setup for the EPC9088 Amplifier Board.

EPC9088 Re V 2.0 Bill of Materials

| Item | Qty | Reference | Part Description | Manufacturer | Part Number |
|------|-----|-------------------------|---------------------|--------------|-------------------|
| 1 | 2 | C10, C20 | 2.2 μ F 100 V | Taiyo Yuden | HMK325B7225KN-T |
| 2 | 1 | C40 | 4.7 μ F, 10 V | Samsung | CL05A475MP5NRNC |
| 3 | 4 | C70, C71, C72, C73 | 100 nF, 16 V | Würth | 885012205037 |
| 4 | 5 | C74, C75, C76, C77, C78 | 22 pF, 50 V | Würth | 885012005057 |
| 5 | 3 | C90, C91, C92 | 1 μ F, 25 V | Würth | 885012206076 |
| 6 | 1 | GP1 | .1" Male Vert. | Würth | 61300111121 |
| 7 | 1 | J62 | .156" Male Vert. | Würth | 645002114822 |
| 8 | 3 | J70, J74, J90 | .1" Male Vert. | Würth | 61300211121 |
| 9 | 1 | Q1 | 150 V 70 m Ω | EPC | EPC2115 |
| 10 | 4 | R72, R73, R77, R78 | 0 Ω | Samsung | RC1005J000CS |
| 11 | 1 | R74 | 10 k | Panasonic | ERJ-2GEJ103X |
| 12 | 1 | R75 | 10 k | Yageo | RC0402FR-0710KL |
| 13 | 1 | U70 | 2 In NAND | Fairchild | NC7SZ00L6X |
| 14 | 3 | U71, U72, U73 | 2 In AND | Fairchild | NC7SZ08L6X |
| 15 | 1 | U90 | 5.0 V 250 mA DFN | Microchip | MCP1703T-5002E/MC |

Optional Components

| Item | Qty | Reference | Part Description | Footprint |
|------|-----|--------------------|---|-----------|
| 1 | 2 | CQ1, CQ2 | Ceramic Capacitor high Q | 1111 |
| 2 | 2 | D77, D78 | Schottky Diode low voltage, low current | SOD-523 |
| 3 | 2 | L10, L20 | Drain Choke large | TBD |
| 4 | 2 | L11, L21 | Drain Choke small | TBD |
| 5 | 2 | Le11, Le21 | Le Inductor Large | TBD |
| 6 | 2 | Le12, Le22 | Le Inductor Small | TBD |
| 7 | 4 | P72, P73, P77, P78 | 1 k Multi-turn potentiometer | PV37W |
| 8 | 1 | R90 | 0 Ω Resistor | CC0603 |

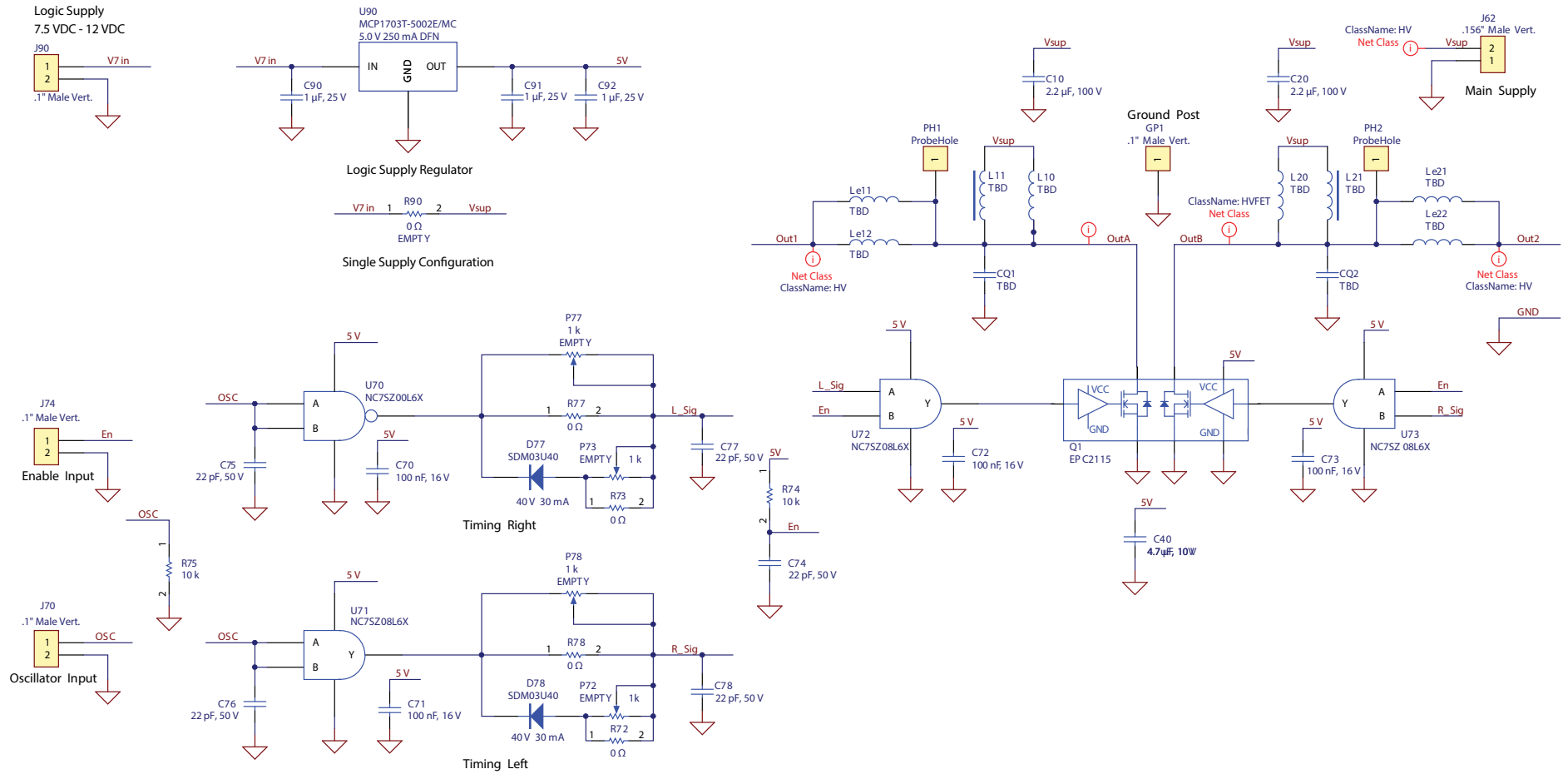


Figure 7: EPC9088 Development board schematic.

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The EPC9088 board is intended for product evaluation purposes only and is not intended for commercial use. Replace components on the Evaluation Board only with those parts shown on the parts list (or Bill of Materials) in the Quick Start Guide. Contact an authorized EPC representative with any questions.

This board is intended to be used by certified professionals, in a lab environment, following proper safety procedures. Use at your own risk.

As an evaluation tool, this board is not designed for compliance with the European Union directive on electromagnetic compatibility or any other such directives or regulations. As board builds are at times subject to product availability, it is possible that boards may contain components or assembly materials that are not RoHS compliant. Efficient Power Conversion Corporation (EPC) makes no guarantee that the purchased board is 100% RoHS compliant.

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